



Call For Papers

The 18th Asian Test Symposium (ATS' 09)

November 23-26, 2009

Evergreen Laurel Hotel, Taichung, Taiwan

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FURTHER INFORMATION

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Objective

The Asian Test Symposium (ATS) provides an open forum for researchers and engineers from all countries of the world, especially from Asia, to exchange innovative ideas on system, board, and device testing with design, manufacturing and field considerations in mind. The official language of the symposium is English.

Scope

Original contributions on testing are solicited. Topics of interest include, but are not limited to, the following categories:

- Automatic Test Generation / Fault Simulation
- Design for Testability / DfX
- Built-In Self-Test
- Test Data Compression
- Delay Testing
- Design Verification
- Low-power Testing
- Defect-Based Testing / IDDX Testing
- Fault Modeling & Diagnosis
- Memory Test / FPGA Test
- Others
- Analog and Mixed-Signal Test
- RF Testing
- High-Speed I/O Test
- System-on-a-Chip Test
- System-in-Package Test
- Board and System Test
- On-line Testing
- Network Protocol Testing / NoC Testing
- Software Testing
- Economics of Test

Submission

Regular Sessions: The ATS'09 Program Committee invites original, unpublished paper submissions on the above topics. Paper submissions should be complete manuscripts, not exceeding six pages (including figures, tables, and bibliography) in a standard IEEE two-column format. Authors should clearly explain the significance of the work, highlight novel features, and describe its current status. On the title page, please include: author name(s) and affiliation(s), and the mailing address, phone number, fax number, and e-mail address of the contact author. A 50-words abstract and five keywords are also required. All submissions are to be made electronically through the ATS'09 website. Electronic submissions in PDF files are strongly recommended. Detailed instructions for submissions are to be found at the ATS'09 website.

The submission will be considered evidence that upon acceptance the author(s) will prepare the final manuscript (6 pages for regular session) in time for inclusion in the proceedings and will present the paper at the Symposium.

Industrial Sessions: This session will address a wide range of practical problems in IC, board and system test, diagnosis, failure analysis, design verification, and so on.

- The session will consist of short oral presentations.
- A one or two pages of abstract is required for submission.
- Each submission should also include the complete address and designate a contact person and a presenter.
- If accepted, a two-page summary will be included in the final proceedings.

Abstract submissions should be emailed to Industry Chair: Dr. Wu-Tung Cheng
(wu-tung_cheng@mentor.com)

Key Dates (Regular Session)

Submission deadline: **May 18, 2009**
Notification of acceptance: **July 10, 2009**
Camera-ready copy: **August 10, 2009**

Key Dates (Industrial Session)

Submission deadline: **June 22, 2009**
Notification of acceptance: **July 10, 2009**
Camera-ready copy: **August 10, 2009**